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FAN1577A

Dual Synchronous DC/DC Controller

Features

- Integrates Two Sets of MOSFET Drivers
- Two Independent PWM Controllers
- Constant Frequency Operation: Free-running Fixed-Frequency Oscillator Programmable: 61kHz to 340kHz
- Maximum Input Supply Voltage: 15V
- Programmable Output as Low as 0.7V
- Internal Error Amplifier Reference Voltage: 0.7V \pm 1.0%
- Two Soft-Start / EN Function Pins
- Programmable Over-Current Protection (OCP)
- 30V HIGH Voltage Pin for Bootstrap Voltage
- Output Over-Voltage Protection (OVP)
- 20-Pin SOP

Applications

- CPU and GPU Vcore Power Supply
- Power Supply Requiring Two Independent Outputs

Description

The FAN1577A is a high-efficiency, voltage-mode, dual-channel, synchronous DC/DC PWM controller for two independent outputs. The two channels are operated out of phase. The internal reference voltage is trimmed to 0.7V \pm 1.0%. It is connected to the error amplifier's positive terminal for voltage feedback regulation.

A soft-start circuit ensures the output voltage can be gradually and smoothly increased from zero to its final regulated value. The soft-start pin can also be used for chip-enable function. When two soft-start pins are grounded, the chip is disabled, and the total operation current can be reduced to under 0.7mA.

The fixed-frequency is programmable from 61kHz to 340kHz. The Over-Current Protection (OCP) level can be programmed by an external current-sense resistor. It has two integrated sets of internal MOSFET drivers.

FAN1577A is available in a 20-pin small-outline package (SOP).

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method
FAN1577AMX	-40°C to +85°C	20-Lead, Small-Outline Package	Tape & Reel

Application Diagram

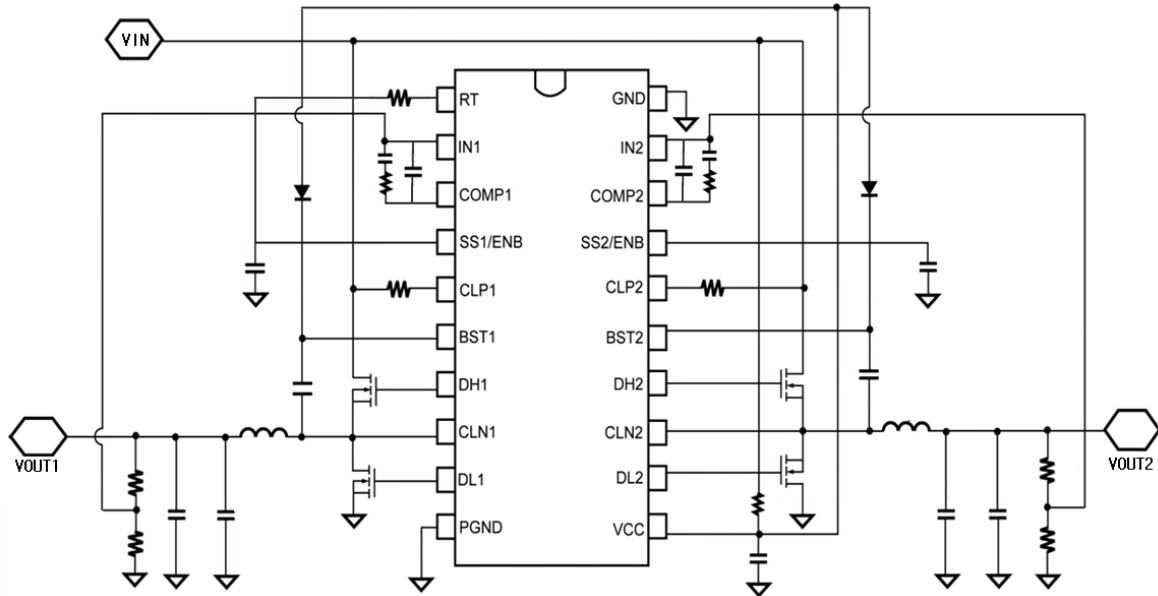


Figure 1. Typical Application

Internal Block Diagram

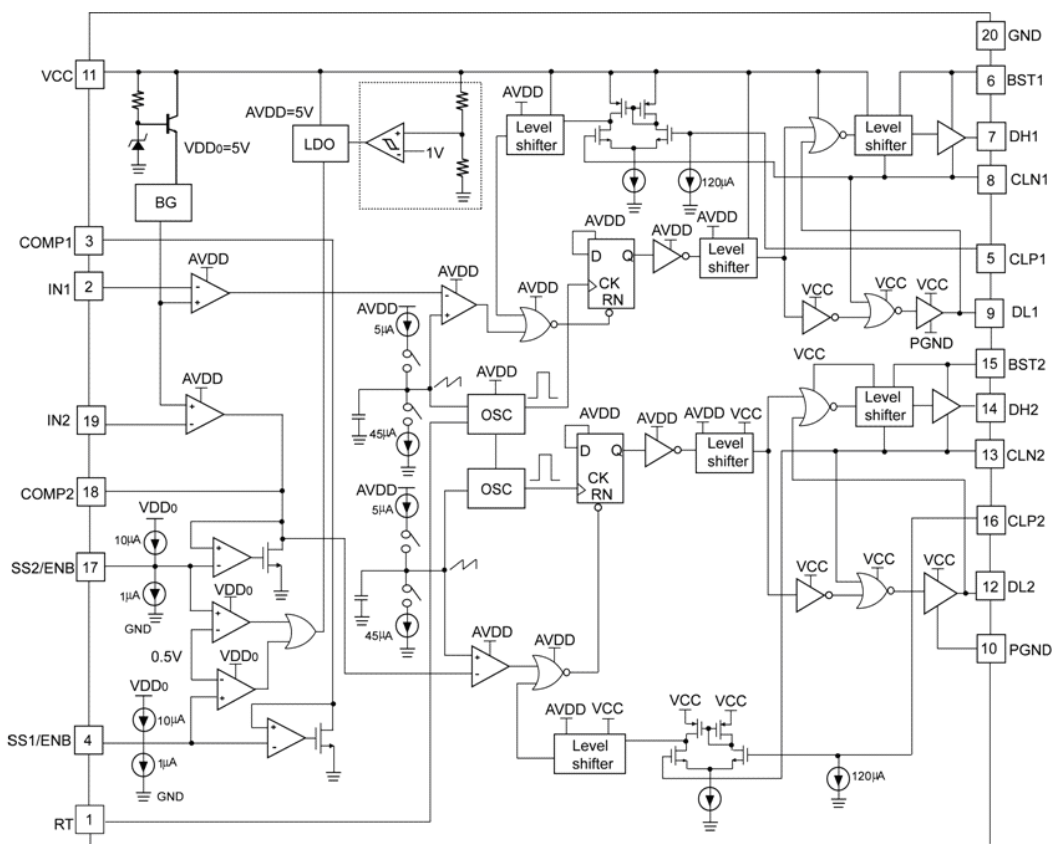


Figure 2. Functional Block Diagram

Pin Configuration & Marking Information

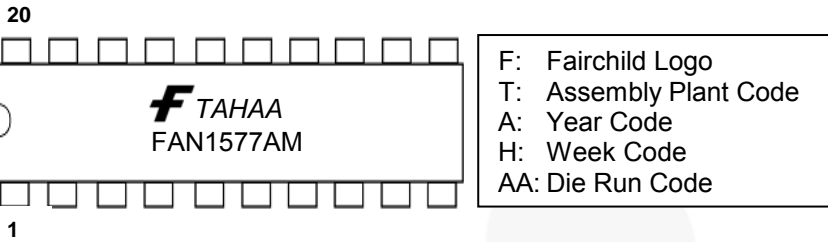


Figure 3. Marking Diagram

F: Fairchild Logo
 T: Assembly Plant Code
 A: Year Code
 H: Week Code
 AA: Die Run Code

Figure 4. Marking Legend

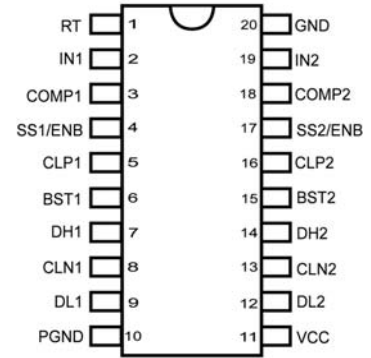


Figure 5. Pin Assignments (Top View)

Pin Definitions

Name	Pin #	Type	Description
RT	1	Frequency Select	An external resistor connecting this pin to GND can program the switching frequency. The switching frequency is 61kHz when RT is open and becomes 340kHz when RT is shorted to ground.
IN1	2	Feedback	Inverting input of the error amplifier normally connected to the switching power supply output through a resistor divider.
COMP1	3	Compensation	Output of the error amplifier and input to the PWM comparator. It is used for feedback-loop compensation.
SS1/ENB	4	Soft-Start / Enable	A 35/15 μ A internal current source charging an external capacitor for soft-start. Pull down this pin and pin 17 to disable the chip.
CLP1	5	Over-Current Protection	Over-current protection for high-side MOSFET. Connect a resistor from this pin to the high-side supply voltage to program the OCP level.
BST1	6	Boost Supply	Supply for high-side driver. Connect to the internal bootstrap circuit.
DH1	7	High-Side Drive	Channel 1, high-side MOSFET gate driver pin.
CLN1	8	Switch Node	Switch-node connection to the inductor. For channel 1, high-side driver's reference ground.
DL1	9	Low-Side Drive	Low-side MOSFET gate driver pin.
PGND	10	Driver Ground	Driver circuit reference. Connect to low-side MOSFET GND.
VCC	11	Power Supply	Supply voltage input.
DL2	12	Low-Side Drive	Low-side MOSFET gate driver pin.
CLN2	13	Switch Node	Switch-node connection to the inductor. For channel 2, high-side driver's reference ground.
DH2	14	High-Side Drive	Channel 2 high-side MOSFET gate driver pin.
BST2	15	Boost Supply	Supply for high-side driver. Connect to the internal bootstrap circuit.
CLP2	16	Over-Current Protection	Over-current protection for the high-side MOSFET. Connect a resistor from this pin to the high-side supply voltage to program the OCP level.
SS2/ENB	17	Soft-Start / Enable	A 35/15 μ A internal current source charging an external capacitor for soft-start. Pull down this pin and pin 4 to disable the chip.
COMP2	18	Compensation	Output of the error amplifier and input to the PWM comparator. It is used for feedback-loop compensation.
IN2	19	Feedback	Inverting input of the error amplifier. It is normally connected to the switching power supply output through a resistor divider.
GND	20	Analog Ground	The reference of internal control circuits.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. All voltage values, except differential voltages, are given with respect to the network ground terminal. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.

Symbol	Parameter	Min.	Max.	Unit
V _{CC}	Supply Voltage, VCC to GND		16	V
BST1(or 2) – CLN1(or 2)	BST1(2) to CLN1(2)		16	V
CLN1(or 2) – GND	CLN1(2) to GND for 100ns Transient	-4	18	V
BST1(or 2) – GND	BST1(2) to GND for 100ns Transient		30	V
DH1(or 2) – CLN1(or 2)			16	V
CLN1(or 2), DL1(or 2)		-0.3	V _{CC} +0.3	V
PGND	PGND to GND		±1	V
θ _{JA}	Thermal Resistance, Junction-Air		70	°C/W
T _J	Operating Junction Temperature	-40	+125	°C
T _{STG}	Storage Temperature Range	-65	+150	°C
ESD	Electrostatic Discharge Protection Level	Human Body Model (HBM)	2	kV
		Charged Device Model (CDM)	1	

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V _{CC}	Supply Voltage		+15	V
T _A	Operating Ambient Temperature	-40	+85	°C

Electrical Characteristics

$V_{CC}=12V$ and $T_A=-40^{\circ}C$ to $+85^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{CC} UVLO						
V_{CC_ON}	Turn-On Threshold	V_{CC} Ramp-Up	9.5	10.0	10.5	V
V_{CC_HYS}	UVLO Hysteresis	V_{CC} Ramp-Down	1.5	2.0	2.5	V
Oscillator						
F_{OSC}	Oscillator Frequency	$R_{RT}=OPEN$	55	61	67	KHZ
		$R_{RT}=GND$	308	340	372	
F_{OSC_RT}	Total Accuracy	$20k\Omega < R_{RT}$	-10		10	%
D_{ON_MAX}	Maximum Duty Cycle		85	90	95	%
Error Amplifier						
V_{REF}	Internal Reference Voltage	$V_{CC}=8V, V_{CC}=15V, T_A=25^{\circ}C$	0.693	0.700	0.707	V
ΔV_{REF}	V_{REF} Temperature Coefficient ⁽¹⁾	$T_A=-40\sim 85^{\circ}C$		0.03		MV/ $^{\circ}C$
A_{VOL}	Open-Loop Voltage Gain			77		DB
BW	Unity Gain Bandwidth			3.5		MHZ
I_{SOURCE}	Output Source Current	$IN1=IN2=0.6V$	60	80	100	μA
I_{SINK}	Output Sink Current	$IN1=IN2=0.8V$	250	400	600	μA
$V_{H_RAMP_PEAK}$	Peak of V_{RAMP}	Gate Output= D_{ON_MAX}	2.45	2.80	3.15	V
V_{RAMP_VALLEY}	Valley of V_{RAMP}	No Gate Output	1.05	1.20	1.35	V
Two-Stage Soft-Start						
I_{SRC_1}	1 st Soft-Start Charge Current	$V_{CLP} < V_{CLN}, V_{SS_Transition} > V_{SS}$	28	35	42	μA
I_{SRC_2}	2 nd Soft-Start Charge Current	$V_{CLP} < V_{CLN}, V_{SS_Transition} < V_{SS}$	13	16	19	μA
$V_{SS_TRANSITION}$	Soft-Start Transition Point	$I_{SOURCE_1}^{st}$ Transit to $I_{SOURCE_2}^{nd}$ See Figure 6	1.40	1.42	1.44	V
I_{SINK}	Soft-Start Discharge Current	$V_{CLP} > V_{CLN}$		50		μA
Protections						
I_{OCSET}	OC Sink Current	$V_{CC}=12V$	90	120	150	μA
T_{OT}	Over-Temperature			150		$^{\circ}C$
T_{OT_HYS}	Over-Temperature Hysteresis			20		$^{\circ}C$
V_{OVP}	Over-Voltage Protection of IN	V_{OVP}/V_{IN}	118	122	126	%
Output						
I_{DH}	High-Side Current Source	$V_{BST} - V_{CLN}=12V, V_{DH} - V_{CLN}=6V$	1.0	1.8		A
R_{DH}	High-Side Sink Resistor	$V_{BST} - V_{CLN}=12V$		2.8	3.8	Ω
I_{DL}	Low-Side Current Source	$V_{CC}=12V, V_{DL}=6V$	1.0	1.8		A
R_{DL}	Low-Side Sink Resistor	$V_{CC}=12V$		2.8	3.8	Ω
T_{DT}	Dead Time ⁽²⁾	$V_{CC}=12V, D_H \& D_L=1000pF$	50	70	90	NS
Total Operating Current						
I_{CC_OP}	Operating Supply Current	$V_{CC}=12V, No Load$	3.3	4.3	5.3	MA
I_{CC_SBY}	Standby Current (Disabled)	$SS1/ENB=SS2/ENB=0V$		0.7	1.0	MA

Notes:

- Not tested in production; 30 pieces sampled.
- When V_{DL} falls less than 2V relative to V_{DH} rising to 2V.

Timing Diagram

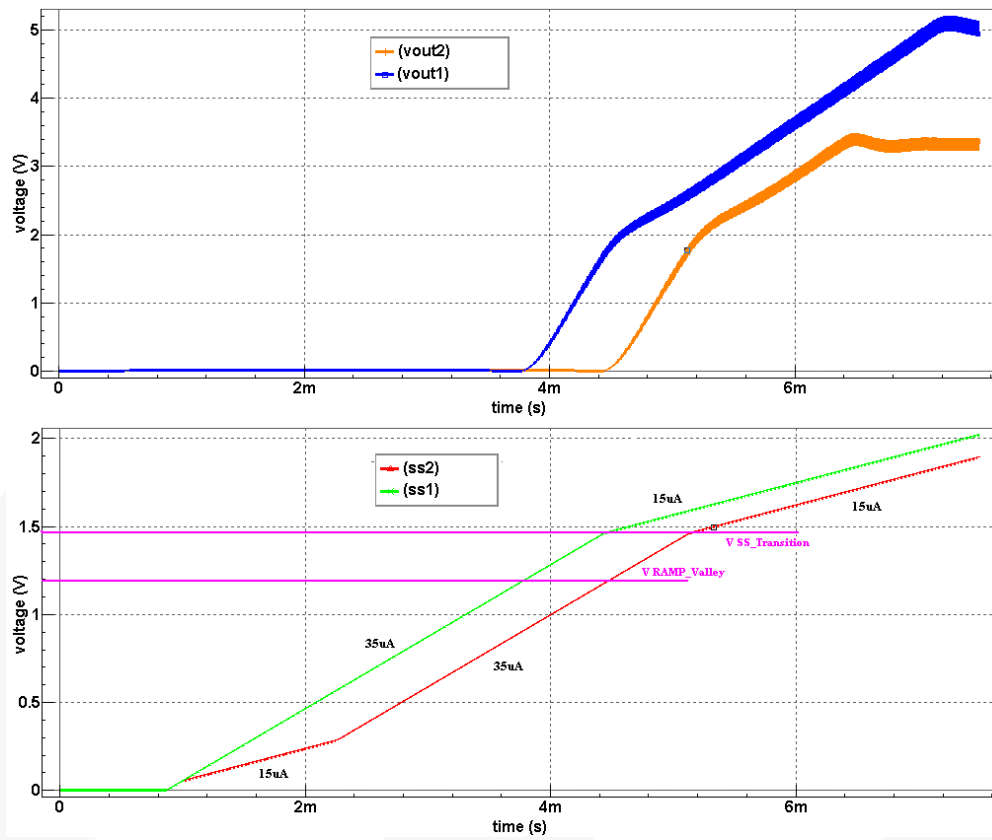


Figure 6. Timing Chart of Two-Stage Soft-Start

Typical Characteristics

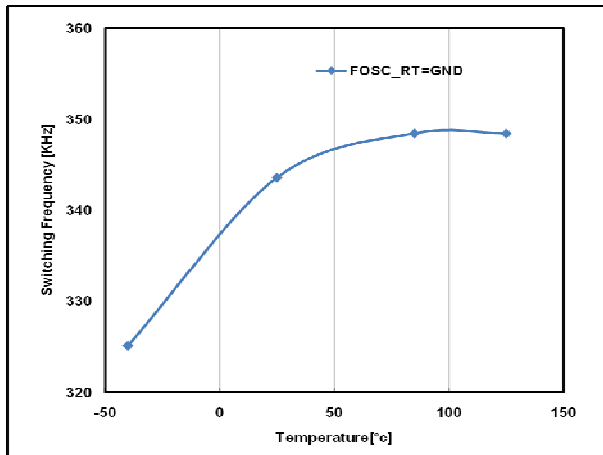


Figure 7. f_{sw} vs. Temperature

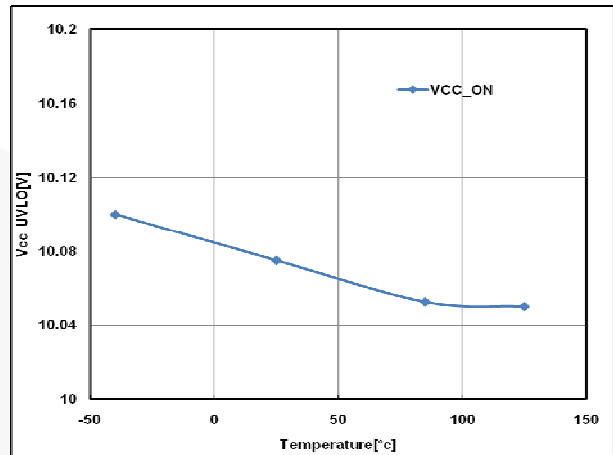


Figure 8. V_{CC_ON} vs. Temperature

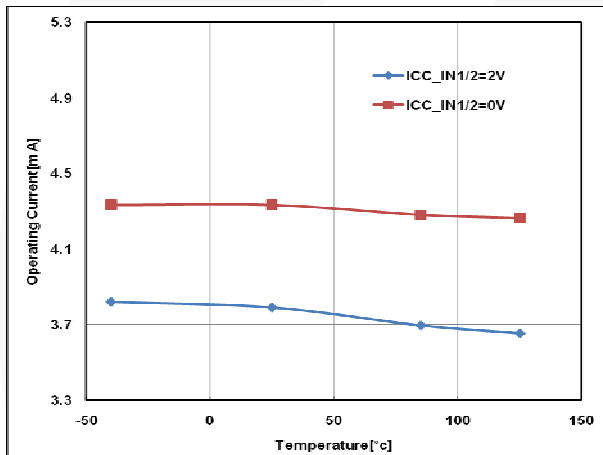


Figure 9. Operating Current vs. Temperature

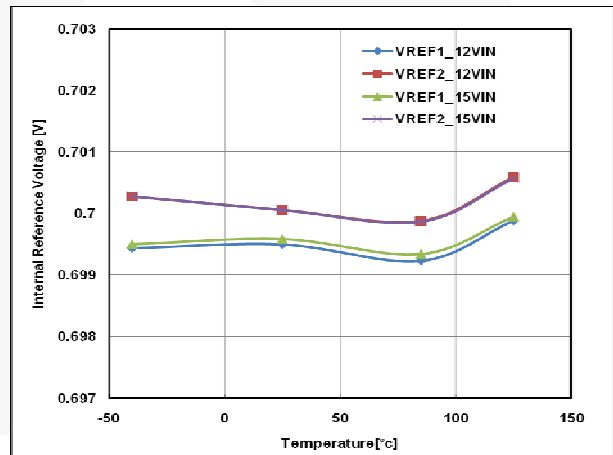


Figure 10. Internal Reference Voltage (V_{REF}) vs. Temperature

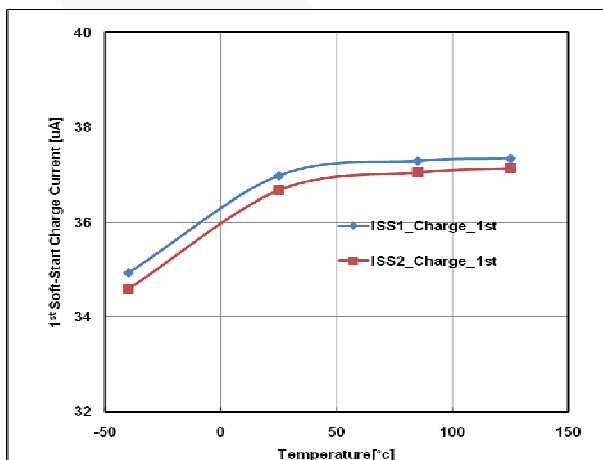


Figure 11. First Soft-Start Charge

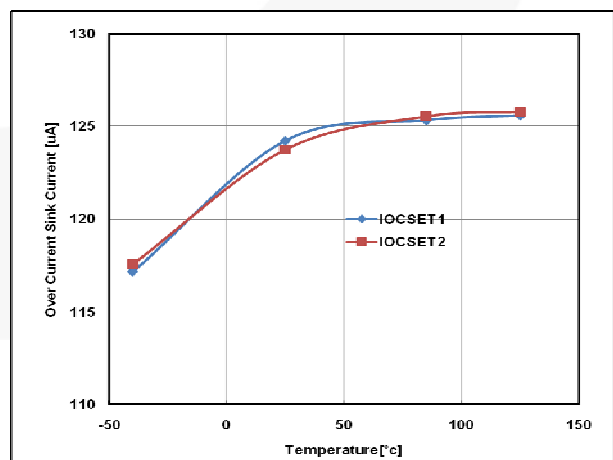


Figure 12. Over-Current Sink Current (I_{ocSET}) vs. Temperature

Typical Performance Characteristics

Unless otherwise noted, values are for $V_{CC}=12V$, $T_A=+25^{\circ}C$, $C_{SS1/ENB}=150nF$, and $C_{SS2/ENB}=168nF$.

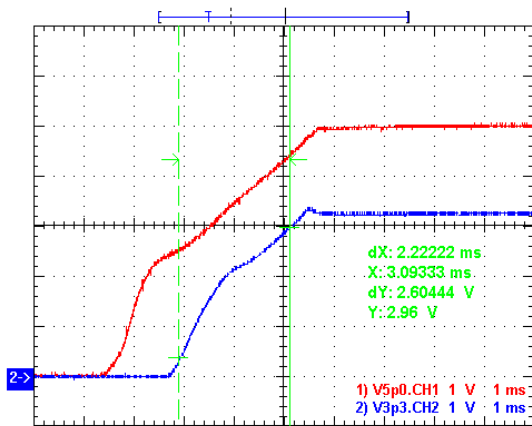


Figure 13. Power On at 0.3A Load

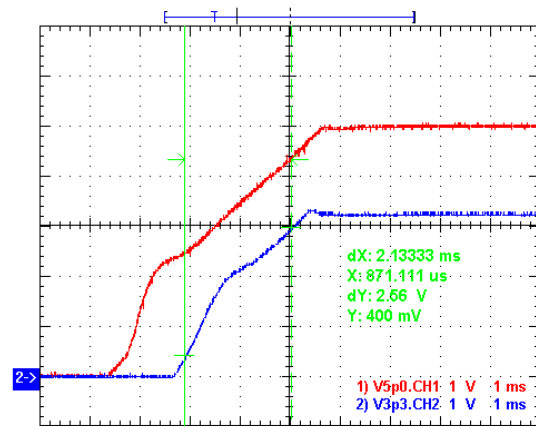


Figure 14. Power On at 3.6A Load

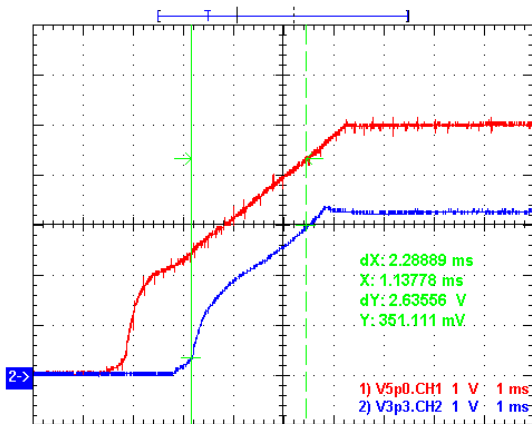


Figure 15. Power On at 9A Load

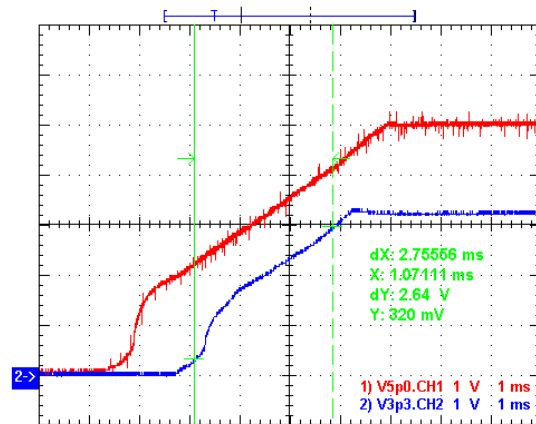


Figure 16. Power On at 18A Load

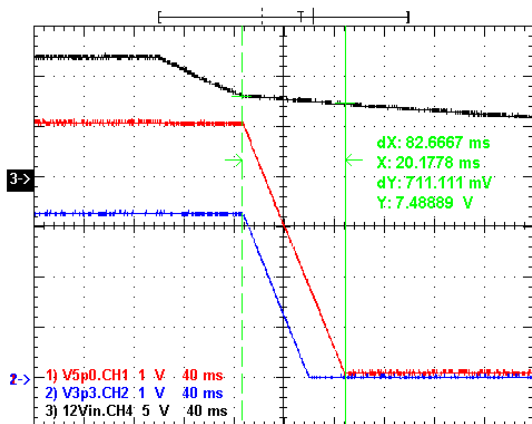


Figure 17. Power Off with 0.3A Load

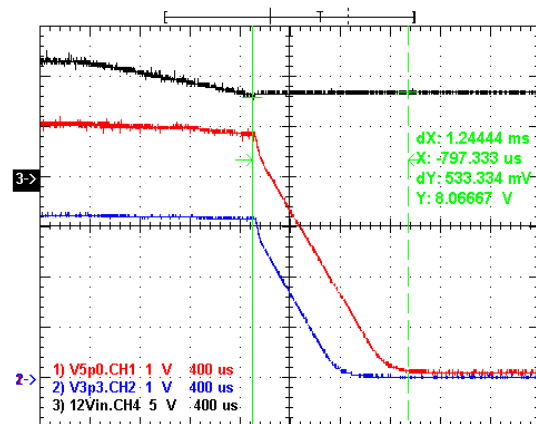


Figure 18. Power Off with 18A Load

Typical Performance Characteristics (Continued)

Unless otherwise noted, values are for $V_{CC}=12V$, $T_A=+25^{\circ}C$, $C_{SS1/ENB}=150nF$, and $C_{SS2/ENB}=168nF$.

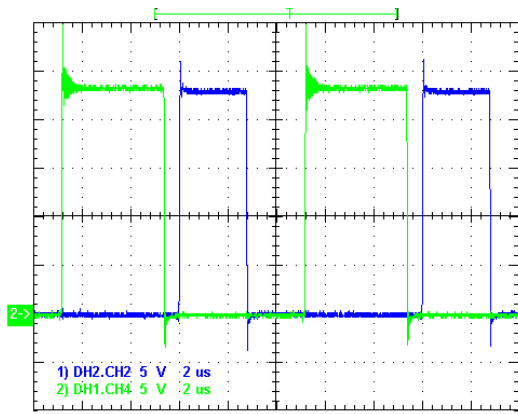


Figure 19. Phase Shift at 0.3A Load

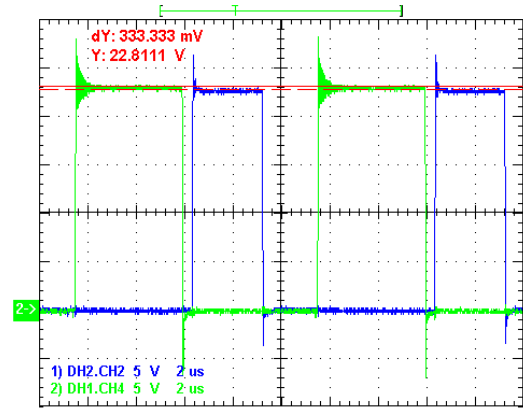


Figure 20. Phase Shift at 18A Load

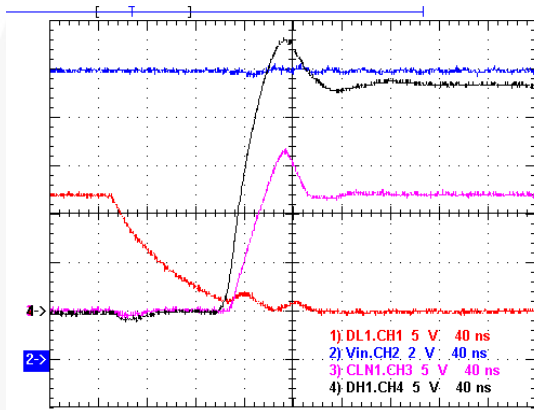


Figure 21. Dead Time at 0.3A Load (Rising Edge)

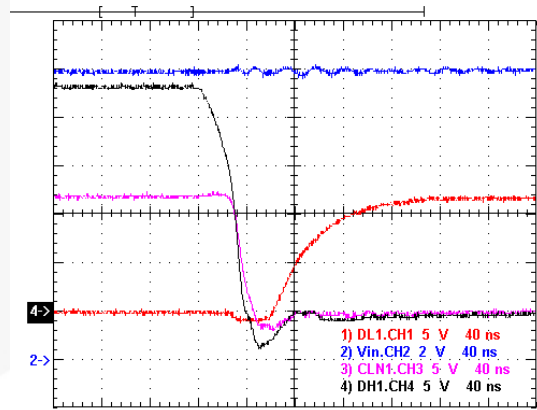


Figure 22. Dead Time at 0.3A Load (Falling Edge)

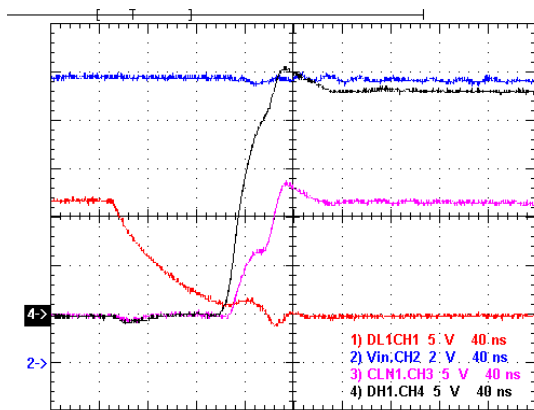


Figure 23. Dead Time at 18A Load (Rising Edge)

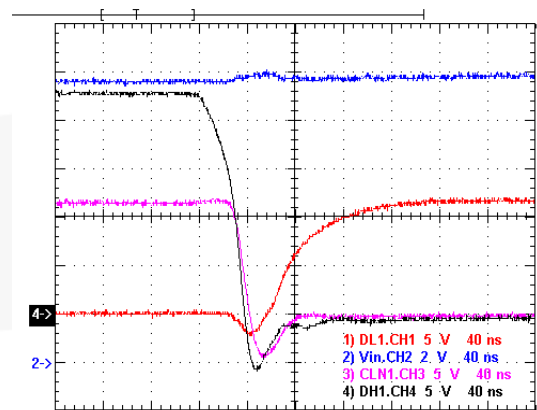


Figure 24. Dead Time at 18A Load (Falling Edge)

Typical Performance Characteristics (Continued)

Unless otherwise noted, values are for $V_{CC}=12V$, $T_A=+25^{\circ}C$, $C_{SS1/ENB}=150nF$, and $C_{SS2/ENB}=168nF$.

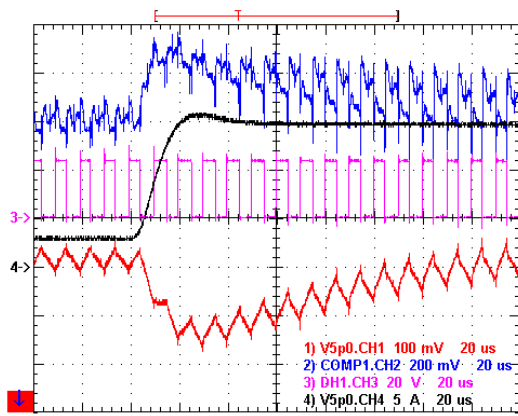


Figure 25. Load Transient Response (Step-Up)
20k Ω /22nF in Compensation Loop

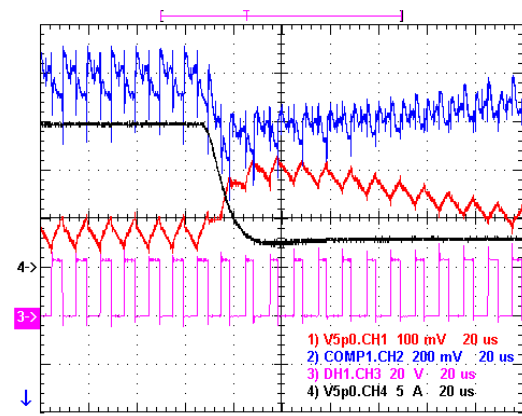


Figure 26. Load Transient Response (Step-Down)
20k Ω /22nF in Compensation Loop

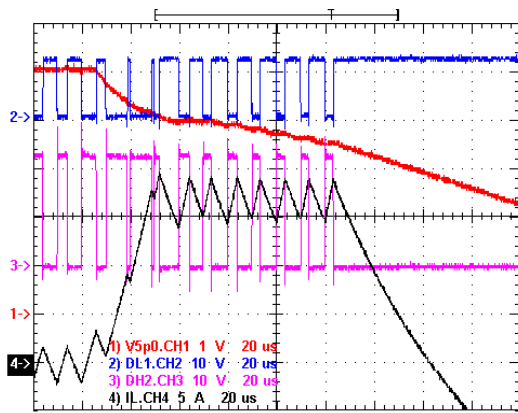


Figure 27. Over-Current Protection (OCP)

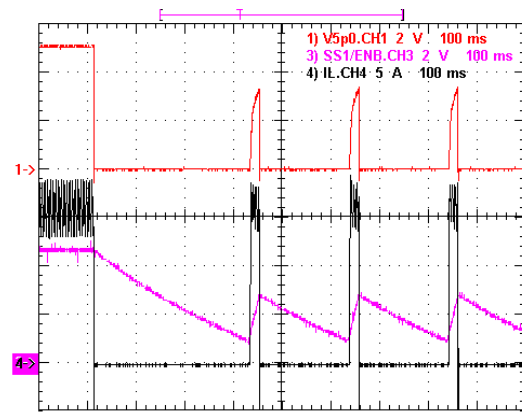


Figure 28. Over-Current Protection ("Hiccup" Mode)

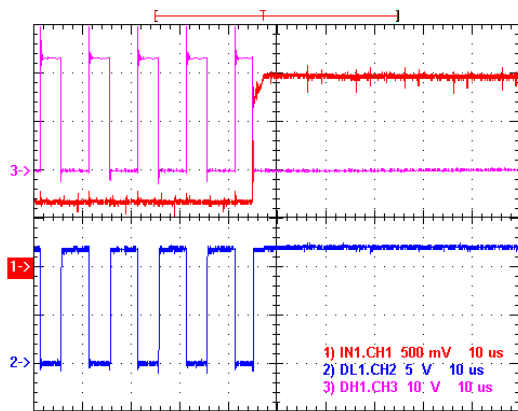


Figure 29. Over-Voltage Protection (OVP)

Functional Description

The FAN1577A is a dual-channel voltage-mode PWM controller with two sets of synchronous MOSFET driving circuits. The two channels are running 180-degrees out of phase. FAN1577A has the following advantages.

Soft Start

An internal startup current (35/15µA) flows out of SS/ENB pin to charge an external capacitor. During the startup sequence, FAN1577A isn't enabled until the SS/ENB pin is higher than 1.2V. From 1.2V to $(1.2 + 1.6 \times D_{ON} / D_{ON_MAX})$ V, the PWM duty cycle gradually increases following the SS/ENB pin voltage to bring output rising. After $(1.2 + 1.6 \times D_{ON} / D_{ON_MAX})$ V, the soft-start period ends and the SS/ENB pin continually rises to 4.8V. When input power is abnormal, the external capacitor on the SS pin is shorted to ground to disable the chip.

$$C_{SS1} \times (1.4V - 1.2V) = 35\mu A \times t_1; C_{SS1} \times (1.2V + 1.6 \times \frac{12}{0.9} - 1.4V) = 15\mu A \times t_2$$

$$; t_1 + t_2 = t_{SS1}$$

$$C_{SS2} \times (1.4V - 1.2V) = 35\mu A \times t_1; C_{SS2} \times (1.2V + 1.6 \times \frac{12}{0.9} - 1.4V) = 15\mu A \times t_2 \quad (1)$$

$$; t_1 + t_2 = t_{SS2}$$

$$C_{SS1} \times 1.2V = 35\mu A \times t_3; \frac{C_{SS2} \times 0.3V}{15\mu A} + \frac{C_{SS2} \times (1.2V - 0.3V)}{35\mu A} = t_4$$

$$; t_4 - t_3 = t_{time_shift}$$

Over-Current Protection (OCP)

Over-current protection is implemented by sensing the voltage drop across the drain and source of the external high-side MOSFET. Over-current protection is triggered when the voltage drop on external high-side MOSFET $R_{DS(ON)}$ is greater than the programmable current-limit voltage threshold. 120µA flowing through an external resistor between input voltage and the CLP pin sets the threshold of current limit voltage. When over-current condition is TRUE, the system is protected against the cycle-by-cycle current limit. A counter counts a series of over-current peak values for eight cycles; the soft-start capacitor is discharged by a 50µA current until the voltage on SS pin reaches 1.2V. During the discharge period, the high-side driver is turned off and the low-side driver is turned on. Once the voltage on the SS/ENB pin is under 1.2V, the normal soft-start sequence is initiated and the 35/15µA current charges the soft-start capacitor again.

$$I_{L(OCP)} = [(R_{SENSE} \times I_{OCSET} + V_{OFFSET}) / R_{DS(ON)} - (V_{IN} - V_{OUT}) \times V_{OUT} / (f_{OSC} \times L_{OUT} \times V_{IN} \times 2)] \quad (2)$$

where V_{OFFSET} ($\cong 10mV$) is the offset voltage contributed by the internal OCP comparator.

Error Amplifier

The IN1 and IN2 pins are connected to the corresponding internal error amplifier's inverting input and the outputs of the error amplifiers are connected to the corresponding COMP1 and COMP2 pins. The COMP1 and COMP2 pins are available for control-loop compensation externally. Non-inverting inputs are internally tied to a fixed 0.7V $\pm 1.5\%$ reference voltage.

Oscillator Operation

The FAN1577A has a programmable-frequency oscillator. The oscillator is running at 61kHz when the RT pin is floating. The oscillator frequency can be adjusted from 61kHz up to 340kHz by an external resistor R_{RT} between the RT pin and ground. The oscillator generates a sawtooth wave that has a 90% rising duty. The sawtooth wave voltage threshold is from 1.2V to 2.8V. The frequency of oscillator can be programmed according to the following equation:

$$f_{OSC}, R_{RT}(kHz) = 61kHz + 8522 / R_{RT}(k\Omega) \quad (3)$$

Setting the Output Voltage

The FAN1577A can be set from 0.7V to 90% of V_{IN} . The output voltages are independently adjusted by voltage dividers (R_1 and R_f in Figure 31) connected to INx. The external resistor dividers can be calculated by:

$$V_{OUT} = 0.7 \times (1 + R_1/R_f) \quad (4)$$

Output Driver

The high-side gate drivers need an external bootstrapping circuit to provide the required boost voltage. The highest gate driver's output (15V is the allowed) on the high-side and low-side MOSFETs forces external MOSFETs to have the lowest $R_{DS(ON)}$, which results in higher efficiency.

Over-Temperature Protection (OTP)

The device is over-temperature protected. When chip temperature is over 150°C, the chip enters 3-state (high-side driver is turned off). The hysteresis is 20°C.

Type II Compensation Design (for Output Capacitors with High ESR)

FAN1577A is a voltage-mode controller. The control loop is a single-voltage feedback path, including an error amplifier and PWM comparator, as shown in Figure 30. To achieve fast transient response and accurate output regulation, an adequate compensator design is necessary. A stable control loop has a 0dB gain crossing with -20dB/decade slope and a phase margin greater than 45°.

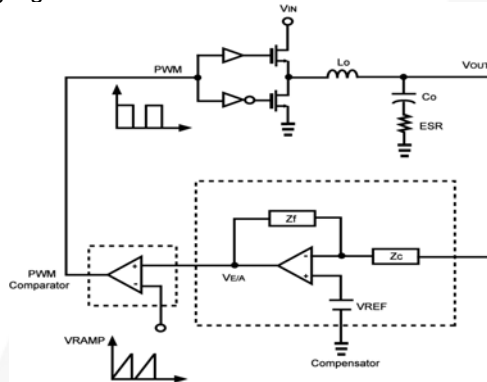


Figure 30. Closed Loop

1. Modulator Frequency Equations

The modulator transfer function is the small-signal transfer function of $V_{OUT}/V_{E/A}$. This transfer function is dominated by a DC gain and the output filter (L_O and C_O) with a double-pole frequency at f_{LC} and a zero at f_{ESR} . The DC gain of the modulator is the input voltage (V_{IN}) divided by the peak-to-peak oscillator voltage $\Delta V_{RAMP}(=1.6V)$. The first step is to calculate the complex conjugate poles contributed by the LC output filter. The output LC filter introduces a double pole, -40dB / decade gain slope above its corner resonant frequency and a total phase lag of 180 degrees. The resonant frequency of the LC filter expressed as:

$$f_{P(LC)} = \frac{1}{2\pi \times \sqrt{L_O \times C_O}} \quad (5)$$

The next step of compensation design is to calculate the ESR zero contributed by the ESR associated with the output capacitance. Note that this requires that the output capacitor have enough ESR to satisfy stability requirements. The ESR zero of the output capacitor is expressed as:

$$f_{Z(ESR)} = \frac{1}{2\pi \times C_O \times ESR} \quad (6)$$

2. Compensation Frequency Equations

The compensation network consists of the error amplifier and the impedance networks Z_c and Z_f as Figure 31 shows.

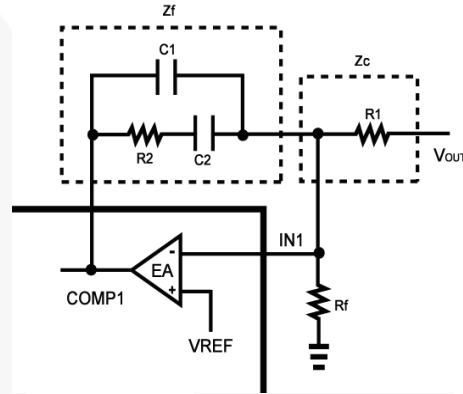


Figure 31. Compensation Loop

$$\begin{aligned} f_{P1} &= 0 \\ f_{Z1} &= \frac{1}{2\pi \times R_2 \times C_2} \\ f_{P2} &= \frac{1}{2\pi \times R_2 \times (C_1 // C_2)} \end{aligned} \quad (7)$$

Compensation gain uses external impedance networks Z_c and Z_f to provide a stable high-bandwidth loop.

High crossover frequency is desirable for fast transient response, but often jeopardizes system stability. To cancel one of the LC filter poles, place the zero before the LC filter resonant frequency. Place the zero at 75% of the LC filter resonant frequency. Crossover frequency should be higher than the ESR zero, but less than 1/5 of the switching frequency. The second pole should be placed at half the switching frequency.

Layout Considerations

Layout is important in high-frequency switching converter design. If designed improperly, PCB can radiate excessive noise and contribute to converter instability.

Place the PWM power-stage components first. Mount all the power components and connections in the top layer with wide copper areas. The MOSFETs of buck, inductor, and output capacitor should be as close to each other as possible to reduce the radiation of EMI due to the high-frequency current loop. If the output capacitors are placed in parallel to reduce the ESR of capacitor, equal sharing ripple current should be considered. Place the input capacitor near the drain of the high-side MOSFET. In multi-layer PCB, use one layer as power ground and have a separate control signal ground as the reference for all signals. To avoid the signal ground being affected by noise and to achieve the best load regulation, it should be connected to the ground terminal of output.

Follow the below guidelines for best performance:

- Keep power traces wide and short to minimize losses and ringing.
- The small-signal wiring traces from the DLx and DHx pins to the MOSFET gates should be kept short and wide enough to easily handle the several amps of drive current.
- The critical, small-signal components include any bypass capacitors (SMD-type of capacitors applied at VCC and SSx/ENB pins), feedback components (resistor divider), and compensation components (between INx and COMPx pins). Position those components close to their pins with a local, clear, GND connection or directly to the ground plane.
- Place the bootstrap capacitor near the BSTx and CLNx pins.
- The resistor on the RT pin should be near this pin and the GND return should be short and kept away from the noisy MOSFET GND (which is shorted together with IC PGND pin to GND plane).
- Place the compensation components close to the INx and COMPx pins.
- The feedback resistors for both regulators should be located as close as possible to the relevant INx pin with vias tied straight to the ground plane as required.
- Minimize the length of the connections between the input capacitors, CIN, and the power switchers (MOSFETs) by placing them nearby.
- Position both the ceramic and bulk input capacitors as close to the upper MOSFET drain as possible and make the GND returns short (from the source of lower MOSFET to GND of V_{IN} capacitor).
- Position the output inductor and output capacitors between the upper MOSFET, lower MOSFET, and the load.
- AGND should be on the clearer plane and kept away from the noisy MOSFET GND.
- PGND should be short, together with MOSFET GND, then through a via to the GND plane.

Physical Dimensions

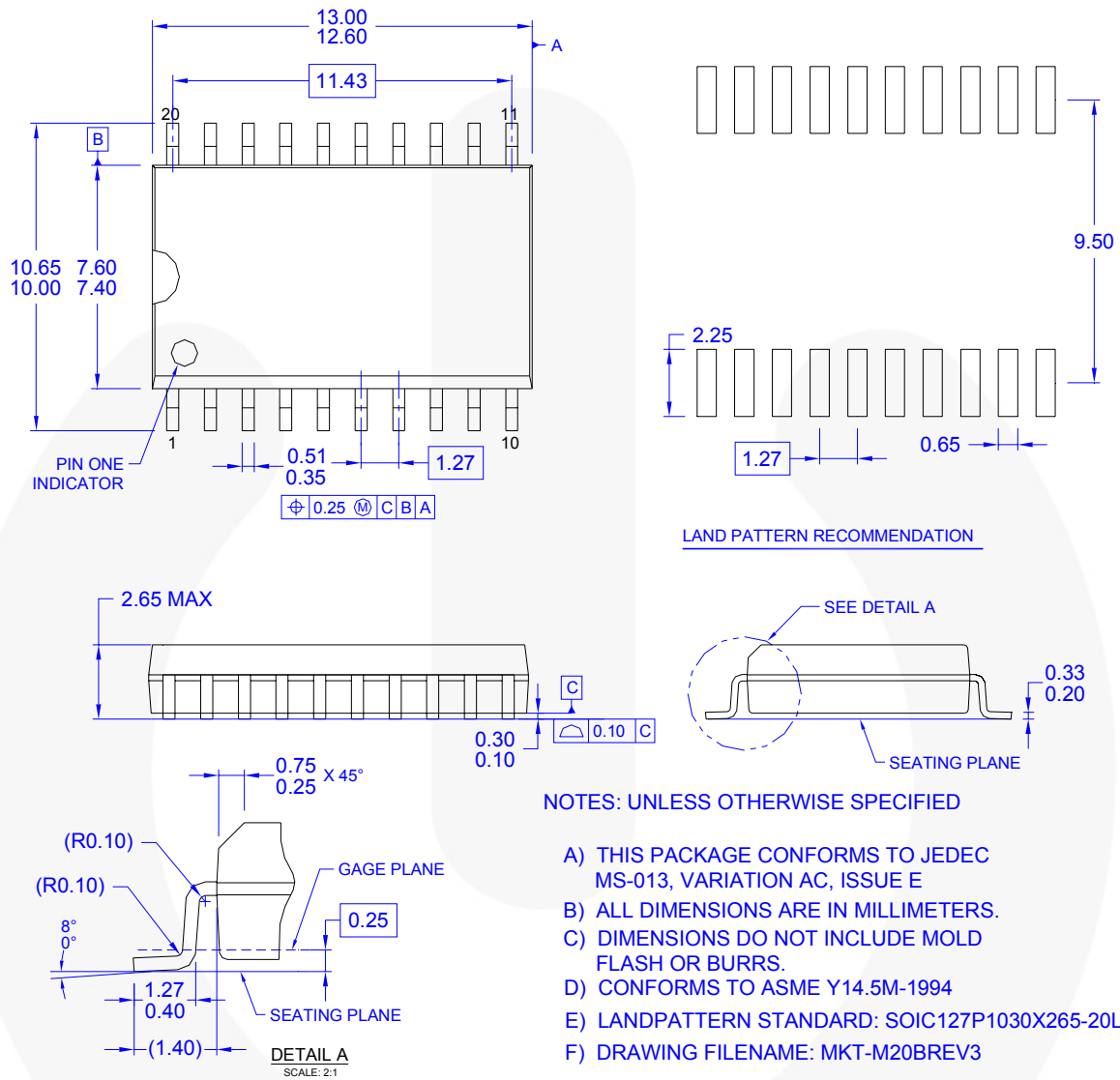


Figure 32. 20-Lead Small Outline Package (SOP)

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